

**Amendments to the Claims:**

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application:

**Listing of Claims:**

1. (Currently Amended) A connection board comprising an insulating resin composition layer formed of ~~one layer or two or more layers~~ at least one sub-layer and a connection conductor which is formed so as to pass through the insulating resin composition layer in its thickness direction at least at a position where a conductor circuit is connected, wherein the connection conductor includes at least two metal layers.

2. (Original) The connection board according to claim 1 further comprising a conductor circuit which is electrically connected to the connection conductor for at least one surface of the connection board.

3. (Original) The connection board according to claim 2, wherein the conductor circuit is a metallic layer.

4. (Original) The connection board according to any one of claims 1 to 3, wherein an exposed portion of the connection conductor is covered with metal.

5. (Currently Amended) The connection board according to any one of claims 1 to 3, wherein ~~one~~ at least one sub-layer of the insulating resin composition ~~composition layer~~ composition layer, placed at at least one of front and rear outermost

layers of the ~~connection board is or both of them are~~insulating resin composition  
layer, is mainly made of thermoplastic resin.

6.-39. (Cancelled)

40. (New) The connection board according to claim 2, wherein each of said at least two metal layers is disposed within said insulating resin composition layer, and said connector conductor is exposed at a surface of the insulating resin composition layer.

41. (New) The connection board according to claim 1, wherein each of said at least two metal layers is disposed within said insulating resin composition layer, and said connector conductor is exposed at a surface of the insulating resin composition layer.

42. (New) The connection board according to claim 41, wherein said at least two metal layers include a first metal layer of a first metal and a second metal layer of a second metal different from the first metal.

43. (New) The connection board according to claim 42, wherein said first metal layer is thicker than said second metal layer, and said second metal is a more expensive metal than said first metal.

44. (New) The connection board according to claim 42, wherein said first metal layer is thicker than said second metal layer.

45. (New) The connection board according to claim 1, wherein at least one sub-layer of the insulating resin composition layer, which is at least one of a front surface layer and a rear surface layer of the insulating resin composition layer, contains a liquid crystal polymer.

46. (New) The connection board according to claim 1, wherein said insulating resin composition layer includes at least two sub-layers.

47. (New) The connection board according to claim 1, wherein said at least two metal layers include a first metal layer of a first metal and a second metal layer of a second metal different from the first metal.

48. (New) The connection board according to claim 47, wherein said first metal layer is thicker than said second metal layer, and said second metal is a more expensive metal than said first metal.

49. (New) The connection board according to claim 47, wherein said first metal layer is thicker than said second metal layer.